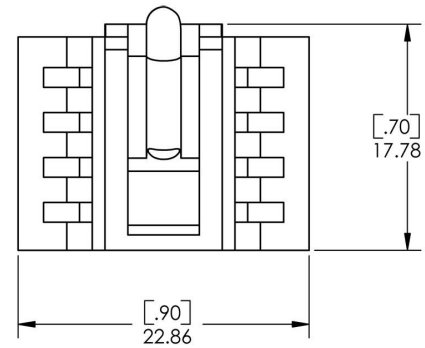
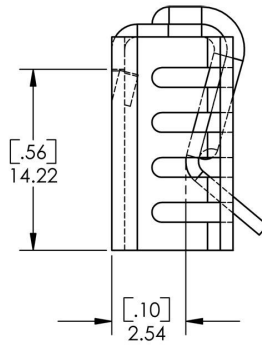
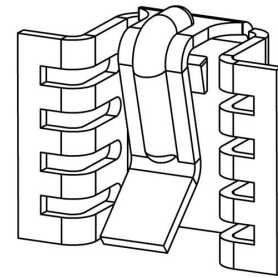
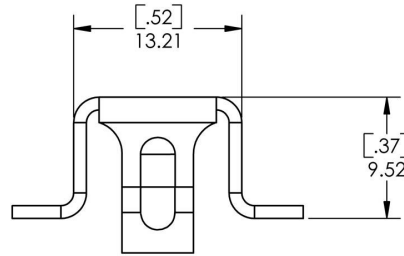
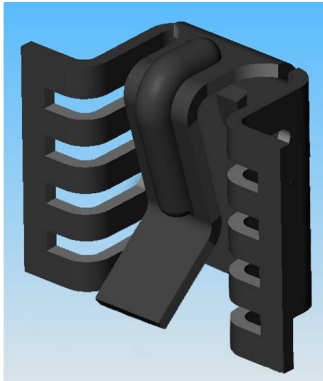


Board Level Heat Sinks



ThermaFlo

P/N: 833502B00000



PRODUCT SPECIFICATIONS

- Devices: TO-220
- Size: 9.5 x 22.8 x 17.8 mm
- Material: Aluminum, 1.0 mm Thick
- Type: Stamped
- IC Mounting: Integrated Spring
- PCB Mounting: Solderable Device Leads
- Finish: Black Anodized
- Package: Bulk

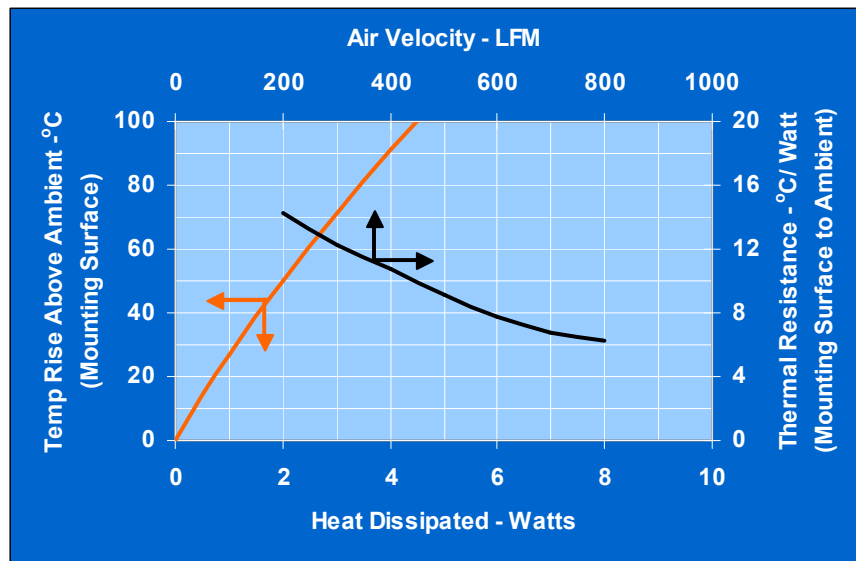
FEATURES & BENEFITS

- No Hardware Device Attachment
- Constant Spring Force Tension
- RoHS Compliant



CUSTOMIZED HEAT SINKS

- Specialized Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-220

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